NOTES:
1. PLACE NET NAMES ON ALL JUMPERS AND HEADERS.
2. PLACE ALL PARTS OTHER THAN SMA CONNECTORS ON A 0, 45 OR 90 DEGREE ORIENTATION.
3. SERIAL DATA SHOULD BE ROUTED AS 60 OHM SINGLE ENDED. ROUTED POWER SHOULD BE A MINIMUM OF 40 MILS WIDE.
4. USE FR4-370 MATERIAL FOR ALL LAYERS.
5. PLACE TI LOGO, BOARD NAME, AND THE BOARD NUMBER IN TOP SIDE METAL.
6. SEE ADDITIONAL NOTES IN SCHEMATIC PAGES

SCHEMATIC SHEET INDEX:

SHEET 01: RS-485 FAN-OUT HUB COVER SHEET AND NOTES
SHEET 02: RS-485 SLAVE DEVICES
SHEET 03: RS-485 MASTER DEVICES
SHEET 04: POWER
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